FEDERAL RESEARCH FUNDING DRIVES MATERIALS SUCCESS





InnoSys, Inc. worked with the National **Aeronautics and Space Administration** to develop a camera that can withstand extreme temperatures and pressure to be mounted on the Venus rover. This work involves microelectronics packaging that includes devices that convert the optical images to electronic signals and then to data that is stored in electronic memory to be sent to earth. It also includes materials to protect electronic devices in harsh conditions. The company received funding from the **Department of Defense** and the **Department of Energy**.

Source: Utah Innovation Center

Microelectronics Packaging

Venus, clouded in intense heat and crushing atmospheric pressure. Exploration devices require advanced materials that can withstand these conditions. Credit: NASA/JPL-Caltech

Federal Funding

The CHIPS and Science Act of 2022 provided \$52.7 billion for US semiconductor research, development, manufacturing, and workforce development, with a 5-year authorization of \$169.9 billion.

The Materials Research Society expertise is at your service

Materials Research Society expertise spans materials in the areas of semiconductors, batteries, and artificial intelligence and machine learning and understands the role of science in helping inform policy. To communicate with an expert, contact MRS at Advocacy@mrs.org.



